# mail

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# MULTILAYER CERAMIC CHIP CAPACITORS



## C Series High Q Capacitors

Type:

C0603 [EIA CC0201]

Issue date:

April 2011

TDK MLCC US Catalog

Version B11

# MULTILAYER CERAMIC CHIP CAPACITORS

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Please read before using this product

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# MULTILAYER CERAMIC CHIP CAPACITORS

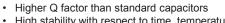


## **C Series** High Q Capacitors

Type: C0603

## Available Through Distribution Only\*

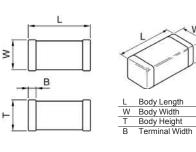
### **Features**



- High stability with respect to time, temperature, frequency, and voltage
- Excellent attenuation
- High self-resonant frequency
- Lower power dissipation/less energy absorption
- Capacitance range of 0.2pF to 15pF
- Available in standard and tight tolerance
- Please contact TDK for Q values

# Shape & Dimensions





### Applications



150 J T XXXX

Internal Codes Packaging Style Packaging Code

Capacitance Tolerance Tolerance Code Tole

Т

W

B C D

E

G

.1

- High-frequency applications
- PA modules
- · Cellular communication, Bluetooth

OVE

- Cable/satellite TV
- · GPS/satellite radio
- Filter networks/matching networks
- RF amplifiers/Low noise amplifiers

Style

Tape & Reel

Tolerance

± 0.05 pF

± 0.10 pF ± 0.25 pF ± 0.50 pF

± 0.20 pF

± 2% ± 5%

- VCOs, TCXOs, etc.
- DC blocking circuits



## Part Number Construction

		C	0603	C0G 1E	
Series Name –					
Dimensions L x	W (mm) –				
Case Code	Length	Width			
C0603	0.60 ± 0.03	$0.30 \pm 0.03$			
Temperature Ch	aracteristic				
Temperature	Capacitance	Temperature			
Characteristics	Change	Range			
C0G	0±30 ppm/°C	-55 to +125°C			
Rated Voltage (I	DC)				l
Voltage Code	Voltage (DC)				
1E	25V				
Nominal Capaci	tance (pF) –				_

The capacitance is expressed in three digit codes and in units of pico Farads (pF). The first and second digits identify the first and second significant figures of the capacitance. The third digit identifies the multiplier. R designates a decimal point.

Capacitance Code	Capacitance
0R5	0.5pF
010	1pF
102	1,000pF (1nF)
105	1,000,000pF (1µF)

* This series is available through the distribution channel only. Ple	lease see <u>www.tdk.com/distributor.php</u> for a list of authorized distributors.
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# MULTILAYER CERAMIC CHIP CAPACITORS



## C0603 [EIA CC0201]

**Capacitance Range Chart** 

Temperature Characteristics: C0G (0 ± 30ppm/°C) Rated Voltage: 25V(1E)

						Tolerance			
Capacitance	Cap Code	Temperature Characteristics	W	В	С	D	Е	G	J
(pF)	Code	Characteristics	(±0.05)	(±0.10pF)	(±0.25pF)	(±0.50pF)	(±0.20pF)	(±2%)	(±5%)
0.2	0R2	-55 to 125ºC,							
0.3	0R3	0±30 ppm/ºC							
0.4	0R4								
0.5	0R5								
0.6	0R6								
0.7	0R7								
0.8	0R8								
0.9	OR9								
1	010	-							
1.1	1R1								
1.2	1R2	-							
1.3 1.5	1R3 1R5								
1.5	1R5 1R6	-							
1.8	1R8								
2	020								
2.2	2R2								
2.4	2R4								
2.7	2R7								
3	030								
3.3	3R3								
3.6	3R6								
3.9	3R9								
4	040								
4.3	4R3								
4.7	4R7								
5	050								
5.1	5R1								
5.6	5R6								
6	060 6R2								
6.8	6R8	-							
7	070								
7.5	7R5								
8	080								
8.2	8R2	1							
9	090								
9.1	9R1	1							
10	100								
11	110								
12	120								
13	130								
15	150								
16	160								
18	180								
20	200								

Standard Thickness

0.30 mm

## MULTILAYER CERAMIC CHIP CAPACITORS



## Capacitance Range Table

## C0603 [EIA CC0201]

### Class 1 (Temperature Compensating)

Temperature Characteristics: COG (-55 to 125°C, 0±30 ppm/°C)

TDK Part Number (Ordering Code)	Temperature Characteristics	Rated Voltage	Capacitance (pF)	Capacitance Tolerance	Thickness (mm)
C0603C0G1E0R2WTQ	COG	25V	0.2	± 0.05pF	0.30 ± 0.03
C0603C0G1E0R2BTQ	COG	25V	0.2	± 0.10pF	0.30 ± 0.03
C0603C0G1E0R3WTQ	COG	25V	0.3	± 0.05pF	0.30 ± 0.03
C0603C0G1E0R3BTQ	COG	25V	0.3	± 0.10pF	0.30 ± 0.03
C0603C0G1E0R4WTQ	COG	25V	0.4	± 0.05pF	0.30 ± 0.03
C0603C0G1E0R4BTQ	COG	25V	0.4	± 0.10pF	0.30 ± 0.03
C0603C0G1E0R5WTQ	COG	25V	0.5	± 0.05pF	0.30 ± 0.03
C0603C0G1E0R5BTQ	COG	25V	0.5	± 0.10pF	0.30 ± 0.03
C0603C0G1E0R6WTQ	COG	25V	0.6	± 0.05pF	0.30 ± 0.03
C0603C0G1E0R6BTQ	COG	25V	0.6	± 0.10pF	0.30 ± 0.03
C0603C0G1E0R7WTQ	COG	25V	0.7	± 0.05pF	0.30 ± 0.03
C0603C0G1E0R8WTQ	COG	25V	0.7	± 0.05pF	0.30 ± 0.03
C0603C0G1E0R7BTQ	COG	25V	0.7	± 0.10pF	0.30 ± 0.03
C0603C0G1E0R8BTQ	C0G	25V	0.8	± 0.10pF	0.30 ± 0.03
C0603C0G1E0R9WTQ	COG	25V	0.9	± 0.05pF	0.30 ± 0.03
C0603C0G1E0R9BTQ	COG	25V	0.9	± 0.10pF	0.30 ± 0.03
C0603C0G1E010BTQ	COG	25V	1.0	± 0.10pF	0.30 ± 0.03
C0603C0G1E010CTQ	COG	25V	1.0	± 0.25pF	0.30 ± 0.03
CO603COG1E1R1BTQ	COG	25V	1.1	± 0.10pF	0.30 ± 0.03
C0603C0G1E1R1CTQ	COG	25V	1.1	± 0.25pF	0.30 ± 0.03
C0603C0G1E1R2BTQ	COG	25V	1.2	± 0.10pF	0.30 ± 0.03
C0603C0G1E1R2CTQ	COG	25V	1.2	± 0.25pF	0.30 ± 0.03
C0603C0G1E1R3BTQ	COG	25V	1.3	± 0.10pF	0.30 ± 0.03
C0603C0G1E1R3CTQ	COG	25V	1.3	± 0.25pF	0.30 ± 0.03
CO603COG1E1R5BTQ	COG	25V	1.5	± 0.10pF	0.30 ± 0.03
C0603C0G1E1R5CTQ	COG	25V	1.5	± 0.25pF	0.30 ± 0.03
C0603C0G1E1R6BTQ	COG	25V	1.6	± 0.10pF	0.30 ± 0.03
C0603C0G1E1R6CTQ	COG	25V	1.6	± 0.25pF	0.30 ± 0.03
C0603C0G1E1R8BTQ	COG	25V	1.8	± 0.10pF	0.30 ± 0.03
C0603C0G1E1R8CTQ	COG	25V	1.8	± 0.25pF	0.30 ± 0.03
C0603C0G1E020BTQ	COG	25V	2.0	± 0.10pF	0.30 ± 0.03
C0603C0G1E020CTQ	COG	25V	2.0	± 0.25pF	0.30 ± 0.03
C0603C0G1E2R2BTX	COG	25V	2.2	± 0.10pF	0.30 ± 0.03
C0603C0G1E2R2CTX	COG	25V	2.2	± 0.25pF	0.30 ± 0.03
C0603C0G1E2R4BTX	COG	25V	2.4	± 0.10pF	0.30 ± 0.03
C0603C0G1E2R4CTX	COG	25V	2.4	± 0.25pF	0.30 ± 0.03
C0603C0G1E2R7BTX	COG	25V	2.7	± 0.10pF	0.30 ± 0.03
C0603C0G1E2R7CTX	COG	25V	2.7	± 0.25pF	0.30 ± 0.03
0603C0G1E030BTX	COG	25V	3.0	± 0.10pF	0.30 ± 0.03
0603C0G1E030CTX	COG	25V	3.0	± 0.25pF	0.30 ± 0.03
C0603C0G1E3R3BTX	COG	25V	3.3	± 0.10pF	0.30 ± 0.03
C0603C0G1E3R3CTX	COG	25V	3.3	± 0.25pF	0.30 ± 0.03
C0603C0G1E3R6BTX	COG	25V	3.6	± 0.10pF	$0.30 \pm 0.03$
C0603C0G1E3R6CTX	COG	25V	3.6	± 0.25pF	$0.30 \pm 0.03$

## MULTILAYER CERAMIC CHIP CAPACITORS



## Capacitance Range Table

## C0603 [EIA CC0201]

#### Class 1 (Temperature Compensating)

Temperature Characteristics: COG (-55 to 125°C, 0±30 ppm/°C)

TDK Part Number (Ordering Code)	Temperature Characteristics	Rated Voltage	Capacitance (pF)	Capacitance Tolerance	Thickness (mm)
C0603C0G1E3R9BTX	COG	25V	3.9	± 0.10pF	$0.30 \pm 0.03$
C0603C0G1E3R9CTX	COG	25V	3.9	± 0.25pF	$0.30 \pm 0.03$
C0603C0G1E040BTX	COG	25V	4.0	± 0.10pF	$0.30 \pm 0.03$
C0603C0G1E040CTX	COG	25V	4.0	± 0.25pF	$0.30 \pm 0.03$
C0603C0G1E4R3BTX	COG	25V	4.3	± 0.10pF	0.30 ± 0.03
C0603C0G1E4R3CTX	COG	25V	4.3	± 0.25pF	0.30 ± 0.03
C0603C0G1E4R7BTX	COG	25V	4.7	± 0.10pF	0.30 ± 0.03
C0603C0G1E4R7CTX	COG	25V	4.7	± 0.25pF	0.30 ± 0.03
C0603C0G1E050BTX	COG	25V	5.0	± 0.10pF	0.30 ± 0.03
C0603C0G1E050CTX	COG	25V	5.0	± 0.25pF	0.30 ± 0.03
C0603C0G1E5R1BTX	COG	25V	5.1	± 0.10pF	0.30 ± 0.03
C0603C0G1E5R1CTX	COG	25V	5.1	± 0.25pF	0.30 ± 0.03
C0603C0G1E5R6BTX	COG	25V	5.6	± 0.10pF	0.30 ± 0.03
C0603C0G1E5R6CTX	COG	25V	5.6	± 0.25pF	0.30 ± 0.03
C0603C0G1E060BTX	COG	25V	6.0	± 0.10pF	0.30 ± 0.03
C0603C0G1E060CTX	COG	25V	6.0	± 0.25pF	$0.30 \pm 0.03$
C0603C0G1E6R2BTX	COG	25V	6.2	± 0.10pF	0.30 ± 0.03
C0603C0G1E6R2CTX	COG	25V	6.2	± 0.25pF	0.30 ± 0.03
CO603COG1E6R8BTX	COG	25V	6.8	± 0.10pF	$0.30 \pm 0.03$
CO603COG1E6R8CTX	COG	25V	6.8	± 0.25pF	0.30 ± 0.03
CO603COG1E070BTX	COG	25V	7.0	± 0.10pF	0.30 ± 0.03
C0603C0G1E070CTX	COG	25V	7.0	± 0.25pF	0.30 ± 0.03
0603C0G1E7R5BTX	COG	25V	7.5	± 0.10pF	0.30 ± 0.03
0603C0G1E7R5CTX	COG	25V	7.5	± 0.25pF	0.30 ± 0.03
CO603COG1E080BTX	COG	25V	8.0	± 0.10pF	0.30 ± 0.03
0603C0G1E080CTX	COG	25V	8.0	± 0.25pF	0.30 ± 0.03
0603C0G1E8R2BTX	COG	25V	8.2	± 0.10pF	$0.30 \pm 0.03$
C0603C0G1E8R2CTX	COG	25V	8.2	± 0.25pF	$0.30 \pm 0.03$
C0603C0G1E090BTX	COG	25V	9.0	± 0.10pF	$0.30 \pm 0.03$
C0603C0G1E090CTX	COG	25V	9.0	± 0.25pF	0.30 ± 0.03
C0603C0G1E9R1BTX	COG	25V	9.1	± 0.10pF	$0.30 \pm 0.03$
0603C0G1E9R1CTX	COG	25V	9.1	± 0.25pF	0.30 ± 0.03
C0603C0G1E100ETX	COG	25V	10	± 0.20pF	$0.30 \pm 0.03$
C0603C0G1E100DTX	COG	25V	10	± 0.50pF	0.30 ± 0.03
C0603C0G1E110GTX	COG	25V	11	± 2%	$0.30 \pm 0.03$
C0603C0G1E110JTX	COG	25V	11	± 5%	0.30 ± 0.03
0603C0G1E120GTX	COG	25V	12	± 2%	0.30 ± 0.03
0603C0G1E120JTX	COG	25V	12	± 5%	0.30 ± 0.03
0603C0G1E130GTX	COG	25V	13	± 2%	$0.30 \pm 0.03$
0603C0G1E130JTX	COG	25V	13	± 5%	0.30 ± 0.03
C0603C0G1E150GTX	COG	25V	15	± 2%	$0.30 \pm 0.03$
C0603C0G1E150JTX	COG	25V	15	± 5%	$0.30 \pm 0.03$
C0603C0G1E160GTX	COG	25V	16	± 2%	$0.30 \pm 0.03$
C0603C0G1E160JTX	COG	25V	16	± 5%	$0.30 \pm 0.03$

TDK MLCC US Catalog

# MULTILAYER CERAMIC CHIP CAPACITORS



## Capacitance Range Table

## C0603 [EIA CC0201]

### Class 1 (Temperature Compensating)

Temperature Characteristics: COG (-55 to 125°C, 0±30 ppm/°C)

TDK Part Number (Ordering Code)	Temperature Characteristics	Rated Voltage	Capacitance (pF)	Capacitance Tolerance	Thickness (mm)
C0603C0G1E180GTX	COG	25V	18	± 2%	0.30 ± 0.03
C0603C0G1E180JTX	COG	25V	18	± 5%	0.30 ± 0.03
C0603C0G1E200GTX	COG	25V	20	± 2%	0.30 ± 0.03
C0603C0G1E200JTX	C0G	25V	20	± 5%	0.30 ± 0.03

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# MULTILAYER CERAMIC CHIP CAPACITORS

General Specifications

## C0603 Series – High Q Capacitors

No.	ltem	Performance		Test or Inspection Method			
1	External Appearance	No defects which may affect performance.		Inspect with magnifying glass (10 $ imes$ ).			
2	Insulation Resistance	10,000MΩ min.		Apply ra	ated voltage for 60s.		
3	Voltage Proof	Withstand test volta insulation breakdow			- - - - - - - - - - - - - - - - - - -		
4	Capacitance	Within the specified tolerance.		Class	Measuring Frequency	Measuring voltage	
				Class 1	1MHz±10%	0.5 - 5 V <sub>rms</sub>	
5	Q	Rated Capacitance	Q	See No.	4 in this table for me	easuring condition.	
	(Class 1)	C ≥ 30pF	1,000 min.				
		C < 30pF 400 + 20×C min.					
		C :	Rated capacitance (pF)				
6	Temperature	T.C. Temperature Coefficient		Temperature coefficient shall be calculated based on			
	Characteristics	C0G 0 ± 30 ppm/°C		values at 25°C and 85°C temperature.			
of Capacitance (Class 1)		Capacitance drift Within $\pm$ 0.2% or $\pm$ 0.05pF, whichever larger.		Measuring temperature below 20°C shall be -10°C and -25°C.			
7	Robustness of Terminations	No sign of termination coming off, breakage of ceramic, or other abnormal signs.			ix 1) and apply a pus	on P.C. board (shown in shing force of 2N for Pushing force	
8	Bending	No mechanical dar	No mechanical damage.		ix 2) and bend it for	on P.C. board (shown in 1mm. $\downarrow$ F R230 45 Unit: mm	

\* This series is available through the distribution channel only. Please see www.tdk.com/distributor.php for a list of authorized distributors.

# MULTILAYER CERAMIC CHIP CAPACITORS



## C0603 Series – High Q Capacitors

9	Solderability	NL					
		termination.	ver over 75% of	Completely soak both terminations in solder at $235\pm5^{\circ}$ C for $2\pm0.5$ s.			
		25% may have p	inholes or rough spots	Solder: H63A (JIS Z 3282)			
		but not concentra		Flux: Isopropyl alcohol (JIS K 8839)			
			of A sections shall not to melting or shifting of rial.	Rosin (JIS K 5902) 25% solid solution.			
			A section				
10	Resistance to se	older heat		Completely soak both terminations in solder at			
	External	No cracks are all	owed and terminations	$260 \pm 5^{\circ}$ C for $5 \pm 1$ s.			
	appearance		at least 60% with new	Preheating condition			
		solder.	1	Temp.: 150±10°C			
	Capacitance	Characteristics	Change from the	Time : 1 to 2min.			
		Class 1 C0G	value before test           Capacitance drift within	Flux: Isopropyl alcohol (JIS K 8839)			
			$\pm 2.5\%$ or $\pm 0.25$ pF,	Rosin (JIS K 5902) 25% solid solution.			
		whichever larger.		Solder: H63A (JIS Z 3282) 			
	Q (Class 1)	Rated Capacitan	ce Q	Leave the capacitor in ambient conditions for 6 to 24h			
		C ≥ 30pF	1,000 min.	before measurement.			
		C < 30pF 400 + 20×C min.		_			
		C	: Rated capacitance (pF				
	Insulation Resistance	Meet the initial sp	Dec.				
	Voltage Proof	No insulation bre damage.	akdown or other	_			
11	Vibration	-		Reflow solder the capacitor on P.C. board (shown in			
	External	No mechanical d	amage	Appendix 1) before testing.			
	appearance	No meenameara	anage.	Vibrate the capacitor with amplitude of 1.5mm P-P			
	Capacitance	Characteristics	Change from the value before test	<ul> <li>sweeping the frequencies from 10Hz to 55Hz and bac to 10Hz after 1min.</li> </ul>			
		Class 1 C0G Capacitance drift within $\pm 2.5\%$ or $\pm 0.25pF$ , whichever larger.		Repeat this for 2h each in 3 perpendicular directions.			
	Q (Class 1)	Rated Capacitan	ice Q				
		C ≥ 30pF	1,000 min.	_			
		C < 30pF	400+20×C min.	_			

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# MULTILAYER CERAMIC CHIP CAPACITORS



## General Specifications

## C0603 Series – High Q Capacitors

No.	Item	Performance			Test or	Inspection Method		
12	<b>Temperature cy</b> External appearance	r <b>cle</b> No mechanical (	dama	ge.	Reflow solder the capacitors on a P.C. board (shown in Appendix 1) before testing. Expose the capacitor in the conditions in step 1			
	Capacitance	Class 1 C0G Capa		hange from the lue before test apacitance drift within 2.5% or $\pm 0.25$ pF,	Leave th	step 4, and repeat 5 times ne capacitor in ambient con neasurement.	2	
				lichever larger.	Step	Temperature (ºC)	Time (min.)	
				-	- 1	Min. operating temp. $\pm$ 3	30 ± 3	
	Q (Class 1)	Rated Capacita	nce	Q	2	Reference Temp.	2-5	
13		C ≥ 30pF		1,000 min.	3	Max. operating temp. $\pm$ 2	30 ± 2	
		C < 30pF		400 + 20×C min.	4	Reference Temp.	2 - 5	
			C : Ra	ated capacitance (pF)				
	Voltage Proof <b>Moisture Resist</b> External	Proof     damage.       Moisture Resistance (Steady State)				solder the capacitor on P.C. ix 1) before testing.	board (shown in	
	appearance	No mechanical	Jama	ige.	Leave at temperature 40±2°C, 90 to 95%RH for 500 +24,0h. Leave the capacitor in ambient condition for 6 to 24h			
	Capacitance	Characteristics		ange from the lue before test				
		Class 1 COG Capacitance drift $\pm 5\%$ or $\pm 0.5pF$ whichever larger.			before measurement.			
	Q (Class 1)	Rated Capacita	nce	Q	_			
	· · · ·	C ≥ 30pF		350 min.				
		10pF ≤ C < 30pF	:	275 + 5/2×C min.				
		C < 10pF		200 + 10×C min.				
		C : Rated capacitance (pF)						
	Insulation Resistance	1,000MΩ min.			-			

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# MULTILAYER CERAMIC CHIP CAPACITORS



## General Specifications

## C0603 Series – High Q Capacitors

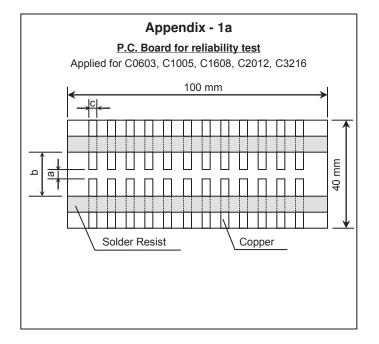
No.	Item	Perform	ance			Test or Inspection Method		
14	Moisture Resist	ance			Reflow solder the capacitors on P.C. board (shown in			
	External	No mechanical damage.				Appendix 1) before testing.		
	appearance					Apply the rated voltage at temperature $40\pm2^{\circ}$ C and $9^{\circ}$ to 95%RH for 500 +24,0h.		
	Capacitance	Charact	eristics		ange from the lue before test	Charge/discharge current shall not exceed 50mA.		
		Class 1	C0G	±7	pacitance drift within 7.5% or $\pm$ 0.75pF, ichever larger.	Leave the capacitor in ambient conditions for 6 to 24h before measurement.		
				1		Use this measurement for initial value.		
	Q (Class 1)	Rated C	apacitan	се	Q			
		C ≥ 30pl			200 min.			
		C < 30pl	=		100 + 10/3×C min.			
			C : Rated capacitance (pF)					
	Insulation Resistance	500MΩ min.				- -		
15	Life					Reflow solder the capacitor on P.C. board (shown in Appendix 1) before testing.		
	External appearance	No mechanical damage.			ge.	Apply 2x rated voltage at $125\pm2^{\circ}$ C for 1,000 +48, 0h.		
	Capacitance	Charact	eristics		ange from the ue before test	Charge/discharge current shall not exceed 50mA.		
		Class 1	C0G	Ca	pacitance drift within $3\%$ or $\pm 0.3pF$ ,	Leave the capacitors in ambient condition for 6 to 24h before measurement.		
					ichever larger.	Use this measurement for initial value.		
	Q (Class 1)	Rated C	apacitan	се	Q			
		C ≥ 30pF			350 min.			
		10pF ≤ 0	C < 30pF		275 + 5/2×C min.			
		C < 10pF	C < 10pF 200 + 10×C min.		200 + 10×C min.			
			C : Rated capacitance (pF)					
	Insulation Resistance	1,000MΩ min.						

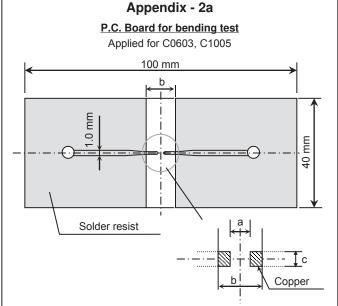
## MULTILAYER CERAMIC CHIP CAPACITORS



### General Specifications

## C0603 Series – High Q Capacitors





Material : Glass Epoxy ( As per JIS C6484 GE4 )

P.C. Board thickness :	Appendix - 2	0.8mm
	Appendix - 1	1.6mm



Copper ( thickness 0.035mm ) Solder resist

Case	Code	Dii	mensions (m	m)
JIS	EIA	а	b	с
C0603	CC0201	0.3	0.8	0.3

## **会TDK**

# MULTILAYER CERAMIC CHIP CAPACITORS



С

В

**Reflow Soldering** 

A B

С

Symbol

Recommended Soldering Land Pattern

Chip capacitor

А

Solder land

Unit: mm

C0603

[CC0201]

0.25 ~ 0.35

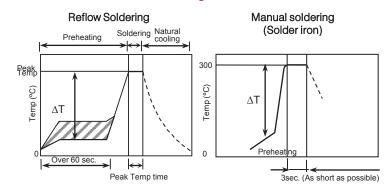
0.2 ~ 0.3

0.25 ~ 0.35

Solder resist

## C0603 Series – High Q Capacitors

### Recommended Soldering Profile



#### **Recommended soldering duration**

Temp./	Reflow Soldering		
Dura. Solder	i car temp	Duration	
Solder	(°C)	(sec.)	
Sn-Pb Solder	230 max.	20 max.	
Lead-Free Solder	260 max.	10 max.	

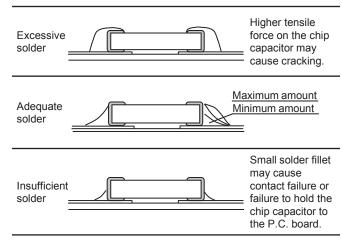
Recommended solder compositions Sn-37Pb (Sn-Pb solder) Sn-3.0Ag-0.5Cu (Lead Free Solder)

#### **Preheating Condition**

Soldering	Temp. (ºC)
Reflow soldering	∆T ≤ 150
Manual soldering	∆T ≤ 150

• Recommended Solder Amount

Туре



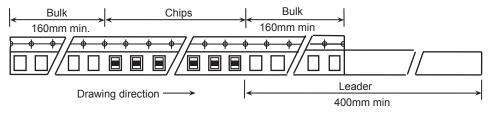
## MULTILAYER CERAMIC CHIP CAPACITORS



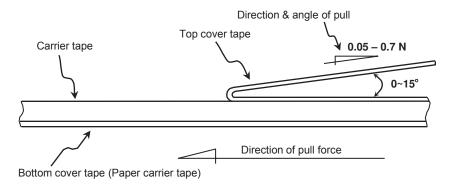
## Packaging Information

## C0603 Series – High Q Capacitors

### • Carrier Tape Configuration



### • Peel Back Force (Top Tape)



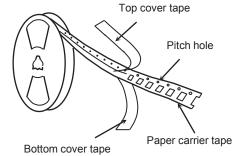
### · Chip Quantity Per Reel and Structure of Reel

• Carrier tape shall be flexible enough to be wound around a minimum radius of 30mm with components in tape.

 $\bullet$  The missing of components shall be less than 0.1%

• Components shall not stick to the cover tape.

• The cover tape shall not protrude beyond the edges of the carrier tape and shall not cover the sprocket holes.



Paper Carrier Tape & Reel

(Bottom cover tape is not always applied)

Case	Code	Chip	Toping	Chip quantity (pcs.)	
JIS	EIA	Thickness (mm)	Taping Material	φ178mm (7") reel	
C0603	CC0201	0.30	Paper	15,000	

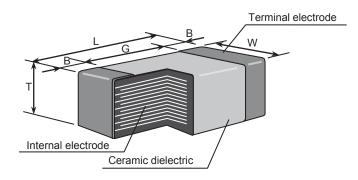
## **谷TD**K

# MULTILAYER CERAMIC CHIP CAPACITORS



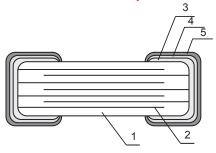
## C0603 Series – High Q Capacitors

• Shape & Dimensions



Case Code		Dimensions (mm)				
JIS	EIA	L	W	Т	В	G
C0603	CC0201	0.60	0.30	0.30	0.15	0.20 min.

### • Inside Structure & Material System



No.	NAME	MATERIAL	
		Class 1	
(1)	Ceramic Dielectric	CaZrO <sub>3</sub>	
(2)	Internal Electrode	Nickel (Ni)	
(3)		Copper (Cu)	
(4)	Termination	Nickel (Ni)	
(5)		Tin (Sn)	

### Environmental Information

TDK Corporation established internal product environmental assurance standards that include the six hazardous substances banned by the EU RoHS Directive<sup>1</sup> enforced on July 1, 2006 along with additional substances independently banned by TDK and has successfully completed making general purpose electronic components conform to the RoHS Directive<sup>2</sup>.

- Abbreviation for Restriction on Hazardous Substances, which refers to the regulation EU Directive 2002/95/EC on hazardous substances by the European Union (EU) effective from July 1, 2006. The Directive bans the use of six specific hazardous substances in electric and electronic devices and products handled within the EU. The six substances are lead, mercury, cadmium, hexavalent chromium, PBB (polybrominated biphenyls), and PBDE (polybrominated diphenyl ethers).
- This means that, in conformity with the EU Directive 2002/95/EC, lead, cadmium, mercury, hexavalent chromium, and specific bromine-based flame retardants, PBB and PBDE, have not been used, except for exempted applications.
- For REACH (SVHC : 15 substances according to ECHA / October 2008) : All TDK MLCC do not contain these 15 substances.
- For European Directive 2000/53/CE and 2005/673/CE : Cadmium, Hexavalent Chromium, Mercury, Lead are not contained in all TDK MLCC.
- For European Directive 2003/11/CE : Pentabromodiphenylether, Octabromodiphenyl-ether are not contained in all TDK MLCC.